

Support for added claims 374-394 is found through the specification. Nonlimiting specific exemplary support for added claims 374-394 is in the figures of U.S. 5,371,654 incorporated by reference in the present application and the figures of the present application.

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Respectfully submitted,

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APPENDIX

Replacement claims 372 and 373:

370 372. (Replacement) A structure, according to claim 356, wherein:

the second substrate is a multi-layer interconnection substrate.

373 373. (Replacement) A structure, according to claim 356, wherein:

the elongated electrical conductor extending from the locations of the surface of
the first substrate comprises a wire.
